

Title (en)
STACKABLE IC PACKAGE WITH TOP AND BOTTOM INTERCONNECT

Title (de)
STAPELBARE IC-KAPSELUNG MIT OBERER UND UNTERER VERBINDUNG

Title (fr)
BOÎTIER DE CIRCUIT IMPRIMÉ EMPILABLE À INTERCONNEXION SUPÉRIEURE ET INFÉRIEURE

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Application
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Abstract (en)
[origin: WO2007148154A1] Consistent with an example embodiment, there is a stackable IC package (218) that comprises a die (206) having a first major surface and a second major surface (212). The first and second major (212) surfaces are joined by opposed pairs of longitudinal (208) and lateral sides (210). A conductive pattern (202) is electrically coupled to the first major surface of the die. The conductive pattern (202) extends past the longitudinal sides of the die and is folded back (204) in a direction (214) generally toward the die. The conductive pattern defines a first portion approximately co-planar with the first major surface of the die and a second portion approximately co-planar with the second major surface of the die. The first and second portions are electrically connectable to another stackable IC package. A support material (216) fixedly supports the conductive pattern (202) relative to the die (206) and supports the first and second portions of the conductive pattern in a spaced, generally parallel relationship to one another.

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